**N-Ch MOSFET** 

#### **General Description**

The WSD60N10GDN56 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSD60N10GDN56 meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

#### **Product Summery**

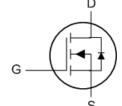
BV <sub>DSS</sub>	R <sub>DSON</sub>	I <sub>D</sub>
100V	8.5mΩ	60A

#### **Applications**

- Power Management in TV Converter.
- DC-DC Converter
- LED TV Back Light

#### **DFN5X6 Pin Configuration**





#### **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units	
$V_{DS}$	Drain-Source Voltage	100	V	
$V_{GS}$	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current	60	А	
I <sub>DP</sub>	Pulsed Drain Current	210	А	
EAS	Avalanche Energy, Single pulse	100	mJ	
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation	125	W	
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	$^{\circ}$	
TJ	Operating Junction Temperature Range	-55 to 150	$^{\circ}$	

#### **Thermal Data**

Symbol	Parameter	Тур. Мах.		Unit	
R <sub>0JA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>		60	°C/W	
Rejc	Thermal Resistance Junction-Case <sup>1</sup>		1.0	°C/W	



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## Electrical Characteristics (T<sub>J</sub>=25 C, unless otherwise noted)

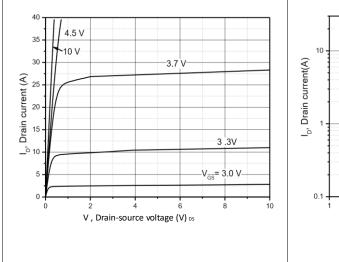
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	100			V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	VGS=10V,ID=10A.		8.5	10.0	mΩ
		VGS=4.5V,ID=10A.		9.5	12.0	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.0		2.5	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =80V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			1	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20V$ , $V_{DS}$ = $0V$			±100	nA
$Q_{g}$	Total Gate Charge (10V)	V <sub>DS</sub> =50V , V <sub>GS</sub> =10V , I <sub>D</sub> =25A		49.9		nC
$Q_{gs}$	Gate-Source Charge			6.5		
$Q_{gd}$	Gate-Drain Charge			12.4		
T <sub>d(on)</sub>	Turn-On Delay Time			20.6		
T <sub>r</sub>	Rise Time	V <sub>DD</sub> =50V , V <sub>GS</sub> =10V ,		5		
T <sub>d(off)</sub>	Turn-Off Delay Time	$R_G=2.2\Omega$ , $I_D=25A$		51.8		ns
T <sub>f</sub>	Fall Time			9		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =50V , V <sub>GS</sub> =0V , f=1MHz		2604		pF
C <sub>oss</sub>	Output Capacitance			362		
C <sub>rss</sub>	Reverse Transfer Capacitance			6.5		
Is	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			60	Α
I <sub>SP</sub>	Pulsed Source Current				210	Α
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>S</sub> =12A , T <sub>J</sub> =25℃			1.3	V
t <sub>rr</sub>	Reverse Recovery Time	lF=12A,dI/dt=100A/μs,T <sub>J</sub> =25°C		60.4		nS
Q <sub>rr</sub>	Reverse Recovery Charge			106.1		nC

### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of  $R_{\theta IA}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_a$ =25 °C.
- 5)  $V_{DD}$ =50 V,  $R_G$ =25  $\Omega$ , L=0.3 mH, starting  $T_i$ =25 °C.



## **Typical Operating Characteristics**



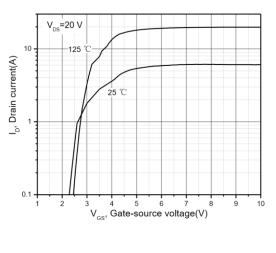
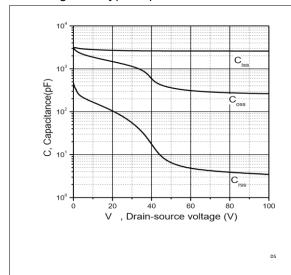


Figure 1, Typ. output characteristics

Figure 2, Typ. transfer characteristics



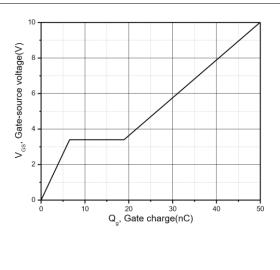
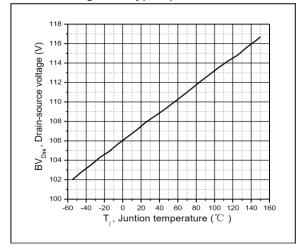


Figure 3, Typ. capacitances

Figure 4, Typ. gate charge



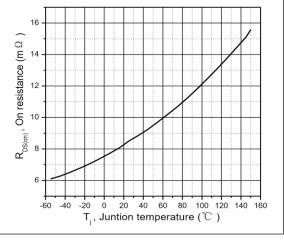
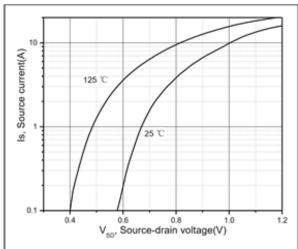


Figure 5, Drain-source breakdown voltage

Figure 6, Drain-source on-state resistance



# **Typical Operating Characteristics (Cont.)**



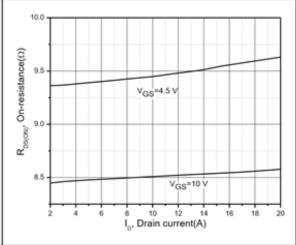
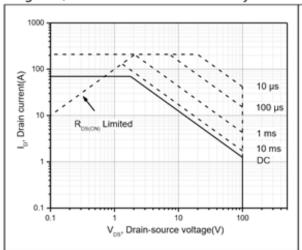


Figure 7, Forward characteristic of body diode

Figure 8, Drain-source on-state resistance





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